


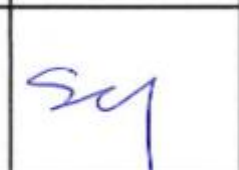


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BF3H50GA-YGH-020mA	B	2019/10/02	1/3

APPROVAL SHEET

Part No: **BF3H50GA-YGH-020mA**

NOTE : **Green Part**

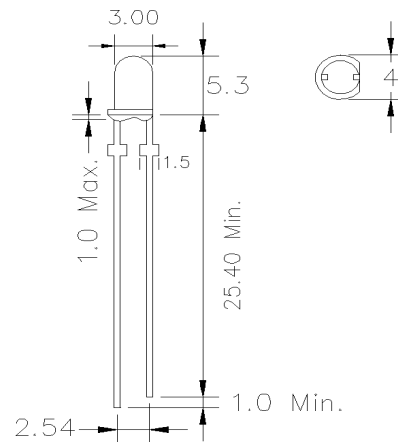
MAKER			CUSTOMER	
				
R&D	QA	Sales	Checked	Approved
				

Prepared	Checked	Approved
Rachel Lee	Sky Lin	Kenneth Wu

LED LAMP Technical Data

DESCRIPTION:

Device Type	: BF3H50GA-YGH-020mA
Dice Material	: AlGaInP/GaAs
Light Color	: Yellow-Green
Lens Color	: Green diffused
Lens Dimension	: 3mm



Absolute Maximum Ratings at Ta=25°C

Parameter	Max.	Unit
DC Forward Current	20	mA
Continuous Forward Current	25	mA
Peak Forward Current (Duty 1/10 @ 1KHZ)	60	mA
Reverse Voltage	5	V
Power Dissipation	50	mW
Operating Temperature	Topr : -40 ~ +80	°C
Storage Temperature	Tstr : -40 ~ +100	°C

Solder DIP (MAX. 5 seconds, 1.6mm from body) Temperature 260°C
Suggest: the better current for this device is less than 20mA.

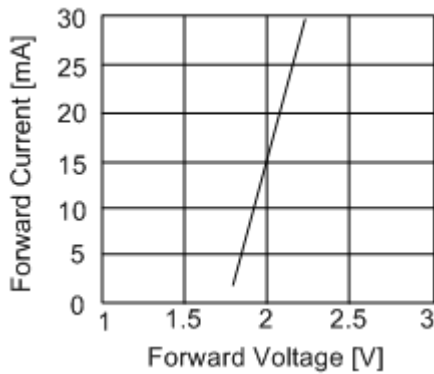
Electrical and Optical Characteristics at Ta=25°C

Symbol	Description	Test Condition	Min.	Typ.	Max.	Unit
V _F	Forward Voltage	I _F = 20mA	1.7	2.1	2.5	V
I _R	Reverse Current	V _R = 5V	-	-	10	μA
λ _p	Peak Wavelength	I _F = 20mA	-	575	-	nm
λ _D	Dom. Emission Wavelength	I _F = 20mA	-	572	-	nm
Δλ	Spectral Line Halfwidth	I _F = 20mA	-	20	-	nm
2θ _{1/2}	Viewing Angle	I _F = 20mA	-	50	-	Deg.
I _v	Luminous Intensity	I _F = 20mA	100	250	-	mcd

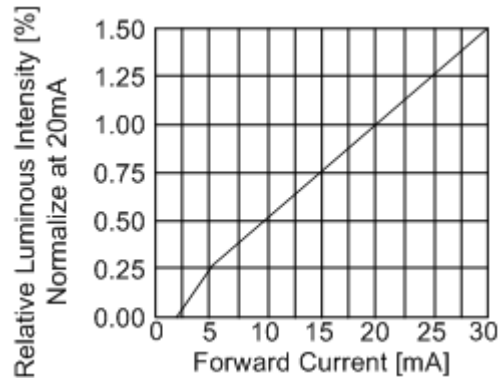
- Note:
- 1.The lead should be formed up to 5mm from the body of device without forming stress.
 2. Soldering shall be performed after lead forming.
 3. All dimensions are in millimeters

LED LAMP Technical Data

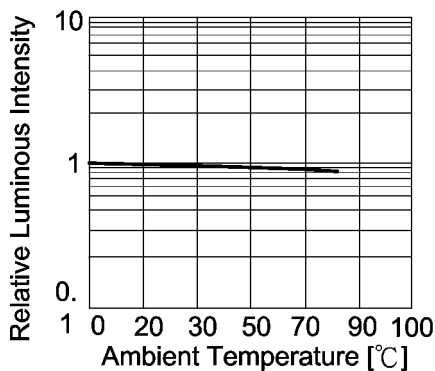
Typical Optical-Electrical Characteristic Curves



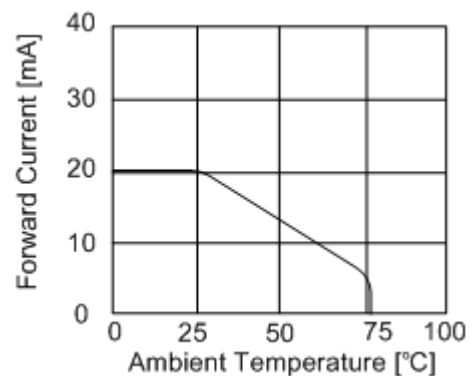
**Forward Current
Vs. Forward Voltage**



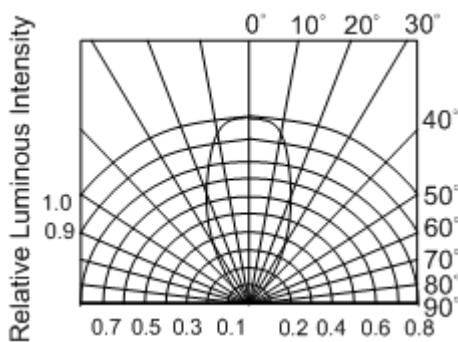
**Forward Current
Vs. Forward Current**



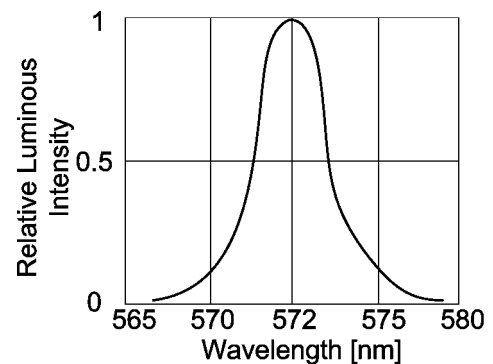
**Luminous Intensity
Vs. Ambient Temperature**



**Forward Current
Vs. Ambient Temperature**



Radiation Pattern



**Relative Luminous Intensity
Vs. Wavelength**